

CALL FOR PAPERS WCSP 2019

5G & Beyond Symposium

October 23-25, 2019, Xi'an, China

http://www.ic-wcsp.org

Overview: The Annual International Conference on Wireless Communications and Signal Processing (IC-WCSP) aims to gather international researchers from academia and industry to meet and exchange ideas and recent research works across the broad field of ICT technologies. The event of WCSP 2019 will be held in Xi'an, Shaanxi, China, on October 23-25, 2019. The theme of WCSP 2019 is to embrace the future communications toward intelligence, including but not limited to wireless communications, future networking, signal processing, 5G Beyond, network and information security, optical communications, satellite communications, intelligent informatics and big data and multimedia.

Scope:

This conference welcomes a variety of topics related to wireless communications, signal processing, and ICT. The scope of the conference includes but not limited to the following areas and topics:

- Quantum communications
- Millimetre-wave and Terahertz communications
- UAV communications
- Molecular communications
- Wireless-powered communication systems
- Fog/edge/cloud
- Cognitive radio communications
- Free-space optical communications
- Beyond 5G wireless channel simulator
- Blockchain technologies
- Wireless Al
- AR/VR & holographic communications
- · Wireless sensor and IoT communications

- Visible light communications
- ICT for sustainable development
- Security for 5G & Beyond
- Graphene photonics
- Beyond 5G wireless channel simulator
- Satellite communications
- Bio signal processing
- · Software-defined radio techniques
- Localization techniques for beyond 5G
- Spectrum and resource virtualization
- Ultra-wideband (UWB) communications
- Future networks
- Photonics technologies for mobile networks

Submission and Publication: Please visit the conference website at http://www.ic-wcsp.org for submission instructions. All accepted and presented papers will be included in the WCSP 2019 Conference Proceedings and submitted for inclusion in **IEEE Xplore** Digital Library.

Important Dates: Submission deadline: June 15, 2019

Acceptance notification: Aug. 15, 2019
Camera-ready paper: Sept. 5, 2019

Symposium Co-Chairs: Qingwen Liu Tongji University, China

Yan Chen Huawei Technology, China

Honggang Wang University of Massachusetts Dartmouth, USA **WeiWei Yang** Army Engineering University of PLA, China